CYStech Electronics Corp.

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Glass Passivated Junction Rectifiers Reverse Voltage 50V to 1000V Forward Current 2.0 Amperes

RL201G thru RL207G

Features

• Low forward voltage drop

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- High current capability
- High reliability
- High surge current capability
- The plastic material carries UL recognition 94V-0

Mechanical Characteristics:

•Case: JEDEC DO-204AC(DO-15) molded plastic

- •Terminals: Tin plated axial leads, solderable per MIL-STD-202E, method 208C
- •Polarity: Color band denotes cathode
- •Mounting position: Any
- •High temperature soldering guaranteed : 250°C/10seconds, 0.375"(9.5mm) lead length at 5 lbs(2.3kg) tension

•Weight : 0.014oz., 0.39grams

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%)

Parameter		Symbol	Туре							I Inita
			RL201G	RL202G	RL203G	RL204G	RL205G	RL206G	RL207G	Units
Maximum Repetitive peak reverse voltage		VRRM	50	100	200	400	600	800	1000	V
Maximum RMS voltage		VRMS	35	70	140	280	420	560	700	V
Maximum DC blocking voltage		VDC	50	100	200	400	600	800	1000	V
Maximum instantaneous forward voltage IF=2A		$V_{\rm F}$	1.1							V
Maximum average forward rectified current, $0.375"(9.5mm)$ lead length at T _A =60°C		IF(AV)	2							А
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)		Ifsm	55							А
Maximum DC reverse current at rated DC blocking voltage	Ta=25°C	Ir	5							μA
	Ta=125°C		100							
Typical junction capacitance (Note 1)		Cj	30							pF
Typical Thermal Resistance		Røja	40							°C/W
Storage temperature range		Tstg	-55 ~ +150							°C
Operating junction temperature range		TJ	-55 ~ +150							°C

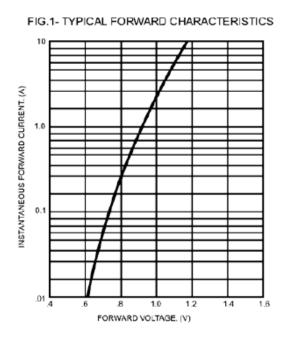
Note: 1. Measured at 1MHz and applied reverse voltage of 4.0VDC





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Ratings and Characteristic Curves



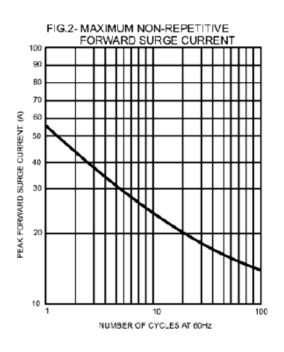
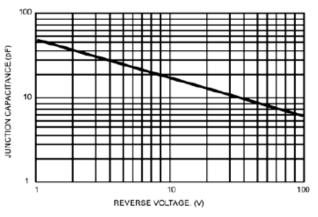
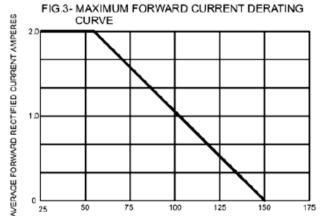


FIG.4- TYPICAL JUNCTION CAPACITANCE

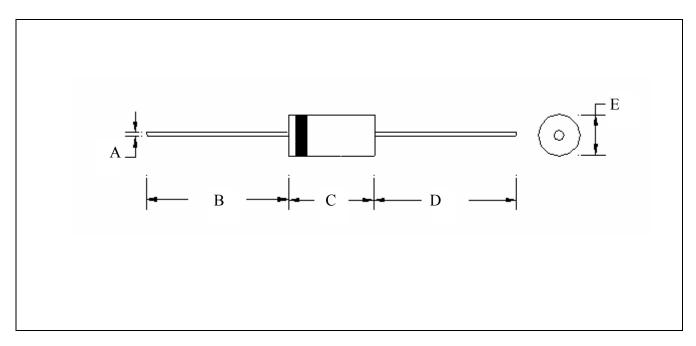




AMBIENT TEMPERATURE. (°C)



DO-204AC(DO-15) Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.	DIN	Min.	Max.	Min.	Max.
A	φ0.028	φ0.034	φ0.70	φ 0.90	D	1.000	-	25.40	-
В	1.000	-	25.40	-	E	φ0.104	φ0.140	φ 2.6 0	φ 3.6 0
С	0.2300	0.3000	5.80	7.60					

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material. 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

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